



8755 W. Higgins Road
Suite 500
Chicago, Illinois USA 60631

April 11th, 2022

RE: PCN # ESU270-78 – SM24CANB-02HTG additional backend location approval

To our valued customers,

Littelfuse would like to notify you of an additional approved backend location for SM24CANB-02HTG TVS Diode Array (SPA® Diodes) product. This additional packaging supplier is necessary to provide stability, in response to the resurgence of the pandemic in Southeast Asia. This additional backend factory, located in China is fully approved for all assembly, test, and packing operation. This factory currently supports commercial and automotive products in the same packages.

Qualification efforts are completed, and the new factory is online for immediate shipments. Please see the documentation in the following pages for change details.

The affected product has been fully qualified in accordance with established performance and reliability criteria. The attached pages summarize the qualification results. Full qualification data and/or samples will be available upon request.

Form, fit, function changes: Nominal differences in package height

Part number changes: None

Effective date: July 11th, 2022 or sooner

Replacement products: N/A

Last time buy: N/A

This notification is for your information and acknowledgement. If you have any other questions or concerns, please contact Sophia Hu, Assistant Product Manager.

We value your business and look forward to assisting you whenever possible.

Best Regards,

Sophia Hu
TVS Diode Array Assistant Product Manager
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Prepared By : Jordan Hsieh-Product Engineering Manager,
Raider Chen-Product Engineer, Sophia Hu- Assistant Product Manager
Date : 2022/3/29
Device : SM24CANB-02HTG
Revision : A

1.0 Objective:

The purpose of this document is to qualify an additional assembly supplier for SM24CANB-02HTG. Summarize the physical, electrical and reliability test performed in qualification lots.

2.0 Applicable Devices:

2.1 **Product name: SM24CANB-02HTG**

3.0 Assembly, Process & Material Differences/Changes:

3.1 **Assembly Changes**

No change of assemble process.

3.2 **Process Changes**

No change of process method.

3.3 **Material Change**

SM24CANB-02HTG			
Item	Original	New	Change or not
Lead frame	C194	CACS5	Yes
Die Attach Material	2200D	84-1LMISR4	Yes
Wire	Gold	Gold	No
Mold Compound	G600	G600	No
Plating	PPF	Matte Tin	Yes

4.0 Packing Method

No change of packing method.

5.0 Physical Differences/Changes:

No change of package dimensions.

6.0 Reliability Test Results Summary:

6.1 SM24CANB-02HTG summary report:

Test Items	Condition	S/S	Results	ETR #
Pre-conditioning (PC)	JESD22-A113	308 each lot	0/924	117689 117690 170510
DC Blocking (HTRB)	Bias = VRWM, Ta = 150°C, Duration = 1008 Hours	77 each lot	0/231	
Temperature Cycle (TC)	Ta = -55°C to +150°C, Duration = 1000 Cycles	77 each lot	0/231	
Temperature/Humidity (H3TRB)	Ta = 85°C, 85% RH, Bias = VRWM, Duration = 1008 Hours	77 each lot	0/231	
Autoclave (AC)	Ta = 121°C, 100%RH, 2ATM, Duration = 96 Hours	77 each lot	0/231	
Resistance to Solder Heat (RSH)	260°C, 10 sec, M-2031	10 each lot	0/30	
Moisture Sensitivity Level (MSL)	Per Jedec J-STD-020D Level 1	308 each lot	0/924	
Solderability (SD)	ANSI-J-STD-002	10 each lot	0/30	

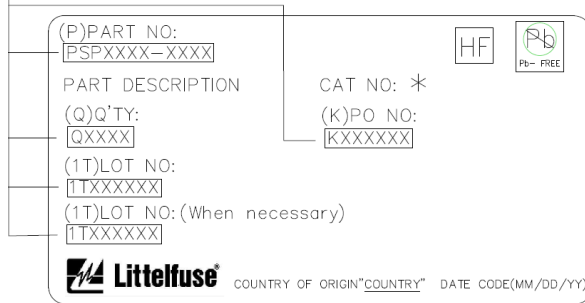
7.0 Electrical Characteristic Summary:

No change in electrical characteristics. Characterization data is available upon request.

8.0 Changed Part Identification:

Below qualified supplier and it can be identified by code of CAT NO on the label.

Barcode Scanning Result



9.0 Approvals:

Sophia Hu
SPA Assistant Product Manager
Littelfuse, Wuxi

Jordan Hsieh
SPA Product Manager
Littelfuse, HsinChu

Raider Chen
SPA Product Engineer
Littelfuse, HsinChu